



DOCUMENT CHANGE REQUEST

DCR number 1075 Changes required for: General

Date: 2017/12/04

Date sent: 2016/12/19

Status: IMPLEMENTED

Originator: Steve Thacker

Organisation: ESCC Executive
Secretariat

Title: DESTRUCTIVE PHYSICAL ANALYSIS OF EEE COMPONENTS

Number: 21001 Issue: 1

Other documents affected:

Page:

Various: see attached draft spec with changes highlighted yellow

Paragraph:

3.1, 3.2, Appendix: 1.4, 1.6, 1.7, 2.1, 16.2, 17

Original wording:

See ESCC No. 21001 issue 1

Proposed wording:

Para 3.1: add missing documents: ESCC 25500, ECSS-Q-ST-70-26

Para 3.2: add missing document: JPL-D-20348

Amend the following appendices as follows:

A1.4, 1.6, 1.7, 2.1, 17: Solderability is MIL-STD-202 Method 208 (was M2011)

A1.4, 1.6, 1.7: Terminal Strength Test is MIL-STD-202 Method 211 (was M2008)

A2.1, 17: add crimp test method : ESCC-Q-ST-70-26.

A2.1, 17: amend Visual Inspection (Test No. 6) to be per ESCC No. 20500 (was MIL-STD-202 M2008)

A16.2: SEM (Test No. 11) is MIL-STD-750 Method 2077 (was MIL-STD-883 M2077)

Justification:

Correction of errors in original issue.

Attachments:
escc21001iss2_draft_a_for_review.docx
Modifications:
N/A
Approval signature:

Date signed:
2017-12-04